

| Test Item | Test Condition | Unit | SPEC | Typical Value |
|----------------------------|----------------------|-------|----------------------|----------------------|
| Tg | DSC | °C | ≥125 | 135 |
| Peel strength(1OZ) | 288°C, 10S | N/mm | ≥1.05 | 1.41 |
| Thermal Stress | 288°C,10S/solder dip | — | >10 | 60S/ No delaminating |
| Flexural Strength | N/mm ² | LW | ≥415 | 500 |
| | | CW | ≥345 | 450 |
| Flammability | E24/125 | — | UL94 V-0 | V-0 |
| Surface Resistivity | After moisture | MΩ | ≥1.0×10 ⁴ | 2.0×10 ⁶ |
| Volume Resistivity | After moisture | MΩ.cm | ≥1.0×10 ⁶ | 2.0×10 ⁸ |
| Dielectric Constant (1MHZ) | 1MHz C-24/23/50 | — | ≤5.4 | 4.7 |
| Dissipation Factor(1MHZ) | 1MHz C-24/23/50 | — | ≤0.035 | 0.017 |
| Loss Tangent | 1MHz C-24/23/50 | — | ≤0.035 | 0.016 |
| Arc Resistivity | D-48/50+D-0.5/23 | S | ≥60 | 135 |
| Dielectric Breakdown | D-48/50+D-0.5/23 | KV | ≥40 | 60 |
| Moisture Absorption | D-24/23 | % | ≤0.8 | 0.15 |
| CTI | IEC60112 Method | V | 175~250 | 210 |

Specimen Thickness:1.6mm

Normal FR-4 CCL

